Unit: mm

2.8 + 0.2

 $1.6^{+0.2}_{-0.1}$

1. GATE 2. SOURCE 3. DRAIN

2-3S1A

JEDEC JEITA

TOSHIBA

Weight: 0.01 g (typ.)

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

SSM3K02T

High Speed Switching Applications

- · Small package
- Low on resistance: R_{on} = 200 m Ω (max) (VGS = 4 V) : R_{on} = 250 m Ω (max) (VGS = 2.5 V)
- Low gate threshold voltage: $V_{th} = 0.6 \sim 1.1 \text{ V (V}_{DS} = 3 \text{ V, I}_{D} = 0.1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Rating	Unit	
Drain-source voltage		30	(v)	
Gate-source voltage		±10)>	
DC	ΙD	2.5	A	
Pulse	I _{DP}	5.0	✓ ^	
Drain power dissipation (Ta = 25°C)		1250	mW	
Channel temperature		150	/%C	
Storage temperature range		-55~150	< ⟨c	
	DC Pulse Ta = 25°C)	VDS VGSS DC ID Pulse IDP Ta = 25°C) PD (Note 1) Tch	VDS 30 VGSS ±10 DC ID 2.5 Pulse IDP 5.0 Ta = 25°C) PD (Note 1) Tch 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in

temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e.

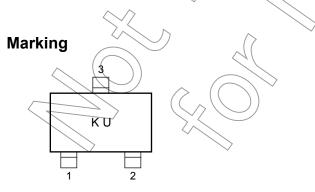
operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions" ("Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

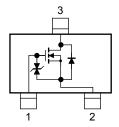
Note 1: Mounted on FR4 board

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ t}, \text{ Cu pad: } 645 \text{ mm}^2, \text{ t} = 10 \text{ s})$

Note 2: The pulse width limited by max channel temperature.



Equivalent Circuit



Handling Precaution

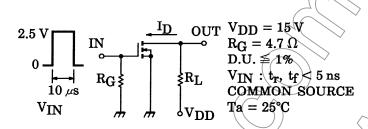
When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

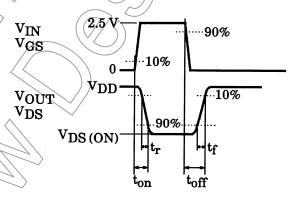
Electrical Characteristics (Ta = 25°C)

Chara	cteristics	Symbol	Symbol Test Condition		Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$	_	_	±5	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 1$ mA, $V_{GS} = 0$	30	_	_	V
Drain cut-off curre	ent	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0$	/	_	1	μА
Gate threshold vo	Itage	V_{th}	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.6	_	1.1	V
Forward transfer a	admittance	Y _{fs}	$V_{DS} = 3 \text{ V}, I_D = 1.25 \text{ A}$ (Note)	2.2) / _	_	S
Drain-source ON resistance		R _{DS (ON)}	$I_D = 1.25 \text{ A}, V_{GS} = 4 \text{ V}$ (Note)	\nearrow	140	200	- mΩ
			I _D = 1.25 A, V _{GS} = 2.5 V (Note)))	180	250	
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz		115	_	pF
Reverse transfer of	capacitance	C _{rss}	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz	^ —	24	_	pF
Output capacitano	ce	C _{oss}	V _{DS} = 10 V, V _{GS} = 0, f = 1 MHz	_	60	_	pF
Switching time	Turn-on time	t _{on}	$V_{DD} = 15 \text{ V}, I_D = 0.5 \text{ A}, V_{GS} = 0~2.5 \text{ V}, R_G = 4.7 \Omega$		52	\rightarrow	- ns
	Turn-off time	t _{off}		-	80	> —	

Note: Pulse test

Switching Time Test Circuit





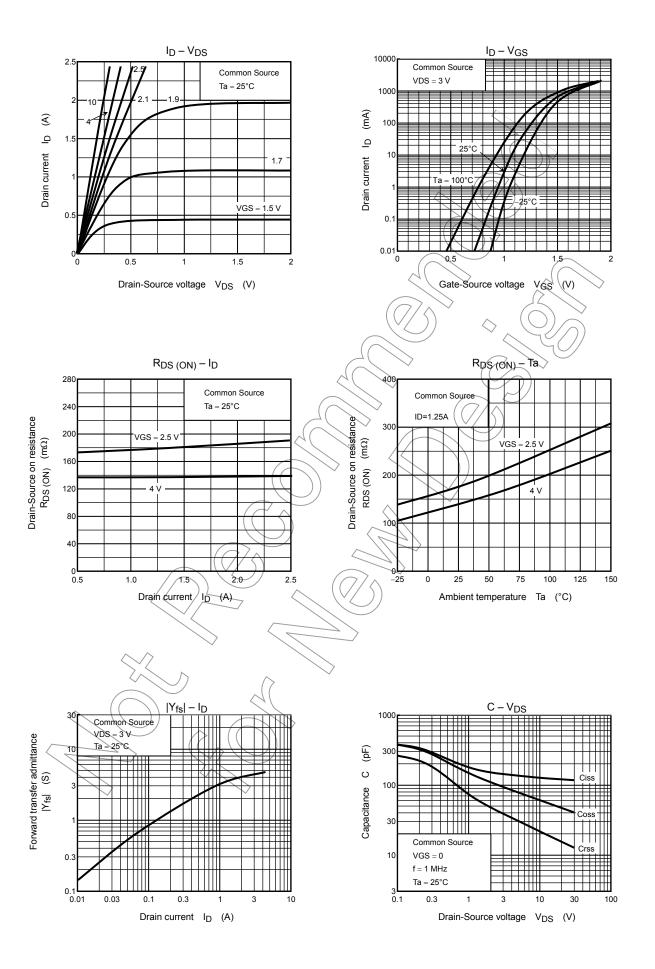
Precaution

 V_{th} can be expressed as voltage between gate and source when low operating current value is ID = 100 μ A for this product. For normal switching operation, VGS (ON) requires higher voltage than V_{th} and VGS (off) requires lower voltage than V_{th} .

(Relationship can be established as follows: VGS (off) < Vth < VGS (ON))

Please take this into consideration for using the device.

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0.001

0.01

0.1

P_D – Ta $t - I_D$ 500 Common Source Mounted on FR4 board **VDD** = 15 V t = 10 $\widehat{\mathbf{S}}$ (25.4 mm \times 25.4 mm \times 1.6 t, 1.25 VGS = 0~2.5 V Cu Pad: 645 mm²) $RG=4.7\;\Omega$ $_{\rm D}$ Ta = 25°C Switching time t (ns) Drain power dissipation 100 0.75 DC 50 0.5 30 ton 0.25 tr 10 ٥L 0.01 0.03 0.3 125 150 0.1 Drain current I_D (A) Ambient temperature Ta√(°C) Safe operating area I_D max (pulsed) ID max (continuous) 10 ms* 3 ₽ DC operation _____Ta = 25°C Drain current Mounted on FR4 board $\begin{array}{c} \text{(25.4 mm} \times \text{25.4 mm} \\ \times \text{1.6 t,} \end{array}$ Cu Pad: 645 mm²) Single nonrepetitive Pulse Ta = 25°C Curves must be derated linearly with increase in temperature. VDSS-max 0.01 0.1 10 Drain-source voltage V_{DS} (V) $r_{th}-tw \\$ 1000 (°C /W) ₹ 100 Transient thermal impedance 10 Mounted on FR4 board (25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 645 mm²)

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1000

100

10

Pulse width tw (s)

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